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(12) **United States Design Patent**
Alfaro et al.

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(54) **CERAMIC BONDING TOOL WITH TEXTURED TIP**

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(**) Term: **15 Years**

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Related U.S. Application Data

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(51) **LOC (11) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/144**

(58) **Field of Classification Search**
USPC D8/29.1, 29.2, 30; D13/123, 133;
D15/122, 138, 144, 144.1, 144.2
(Continued)

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(57) **CLAIM**

The ornamental design for a ceramic bonding tool with textured tip, as shown and described.

DESCRIPTION

FIG. 1 depicts a perspective view of a ceramic bonding tool with textured tip.

FIG. 2 depicts a side elevation view of the ceramic bonding tool with textured tip of FIG. 1.

FIG. 3 depicts a top plan view of the ceramic bonding tool with textured tip of FIG. 1.

FIG. 4 depicts a bottom plan view of the ceramic bonding tool with textured tip of FIG. 1.

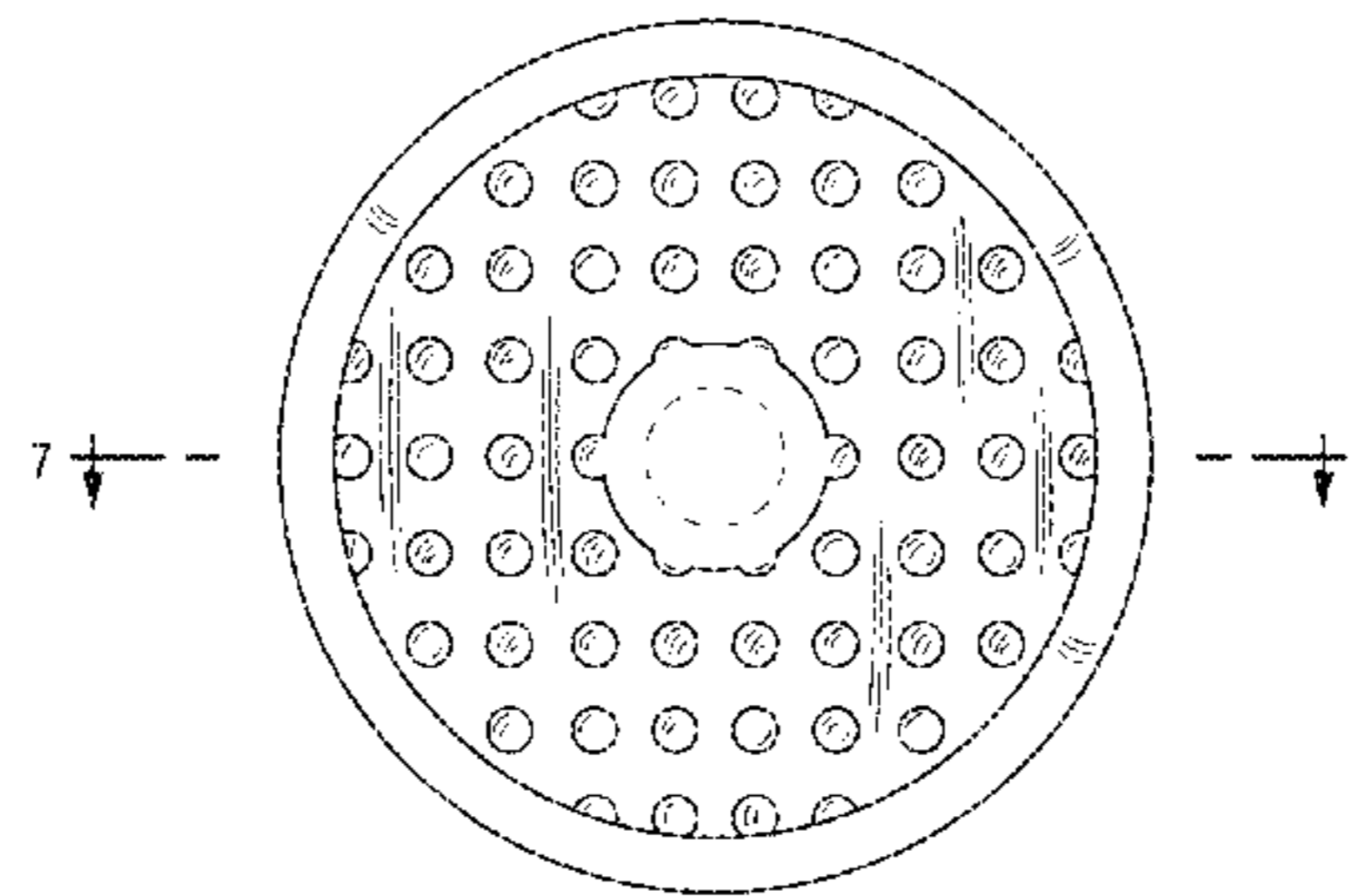
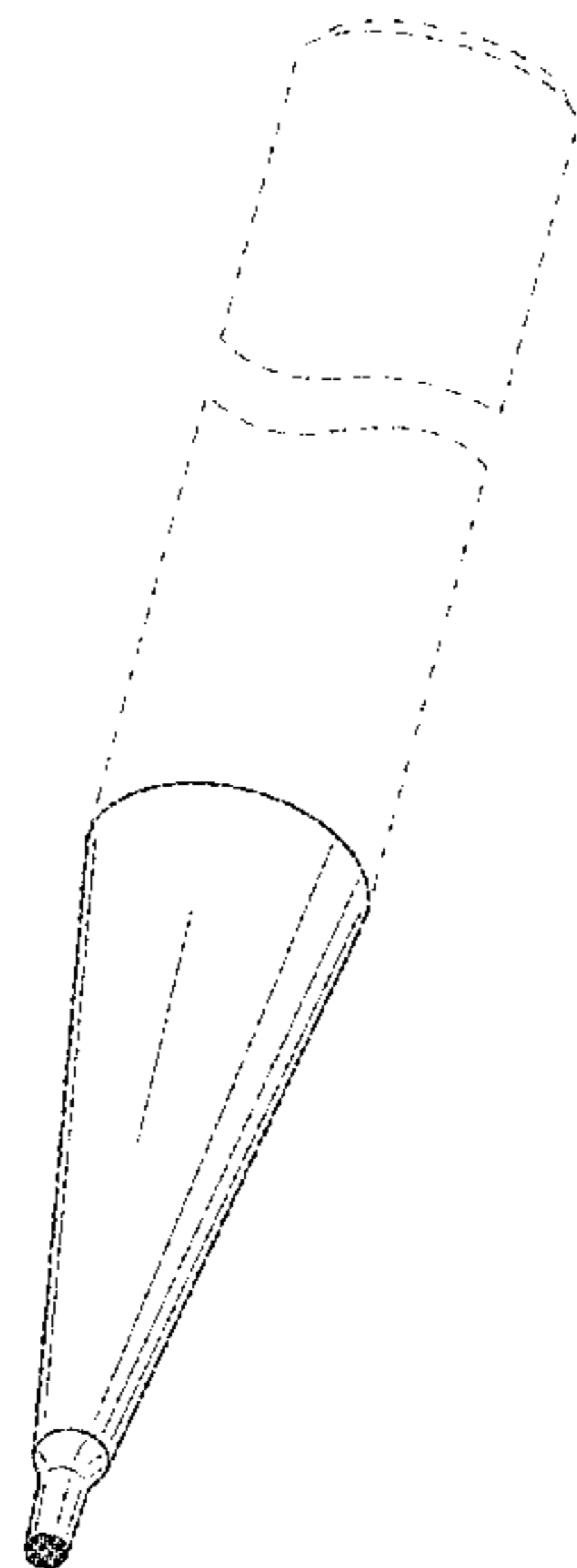
FIG. 5 depicts detailed side elevation view of the ceramic bonding tool with textured tip of FIG. 1.

FIG. 6 depicts a detailed bottom plan view of the ceramic bonding tool with textured tip shown in FIG. 4; and,

FIG. 7 depicts a detailed side cross-sectional view of the ceramic bonding tool with textured tip, the cross-section taken along cross-section indicator line 7-7 of FIG. 6.

The broken lines in the drawings illustrate environmental structure on the article and form no part of the claimed design.

1 Claim, 4 Drawing Sheets



(58) **Field of Classification Search**
 CPC .. B23K 20/004; B23K 20/005; B23K 20/106;
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 See application file for complete search history.

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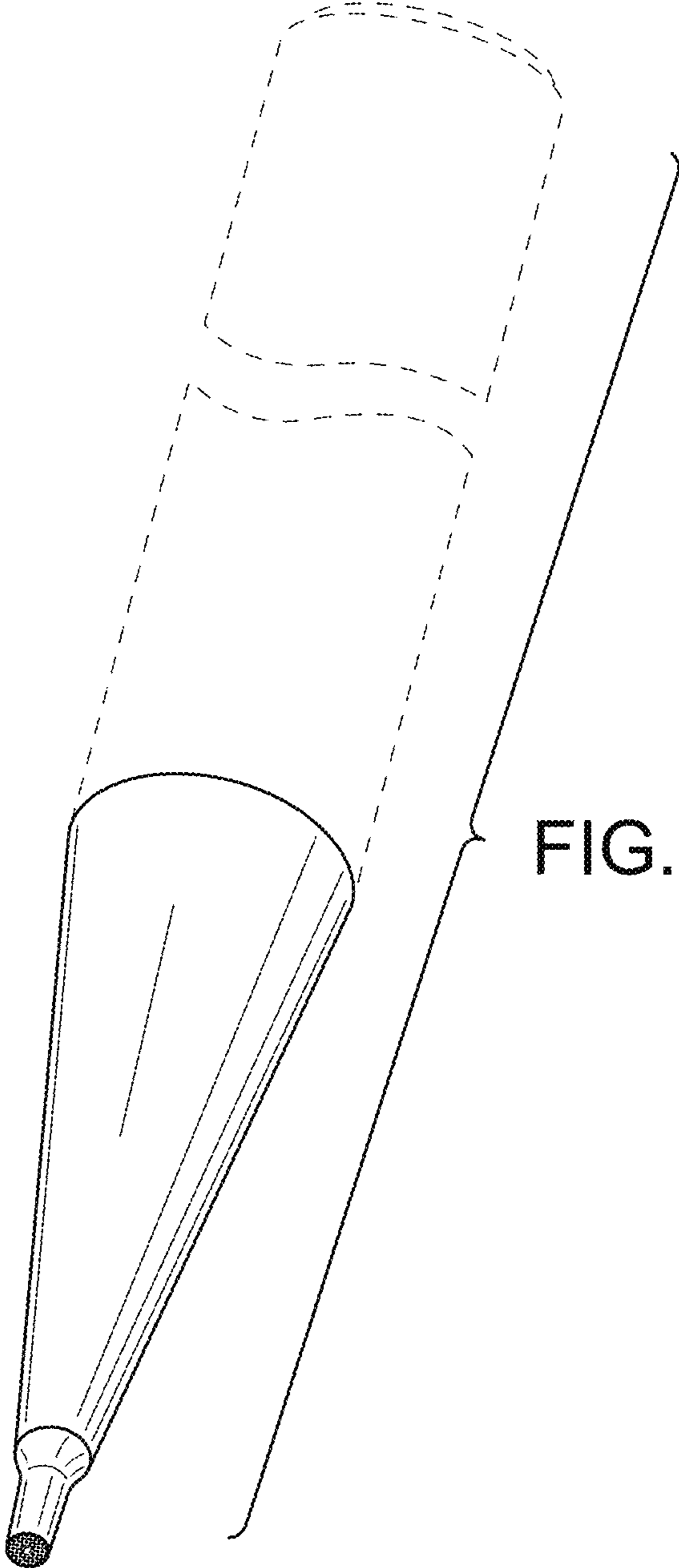


FIG.1

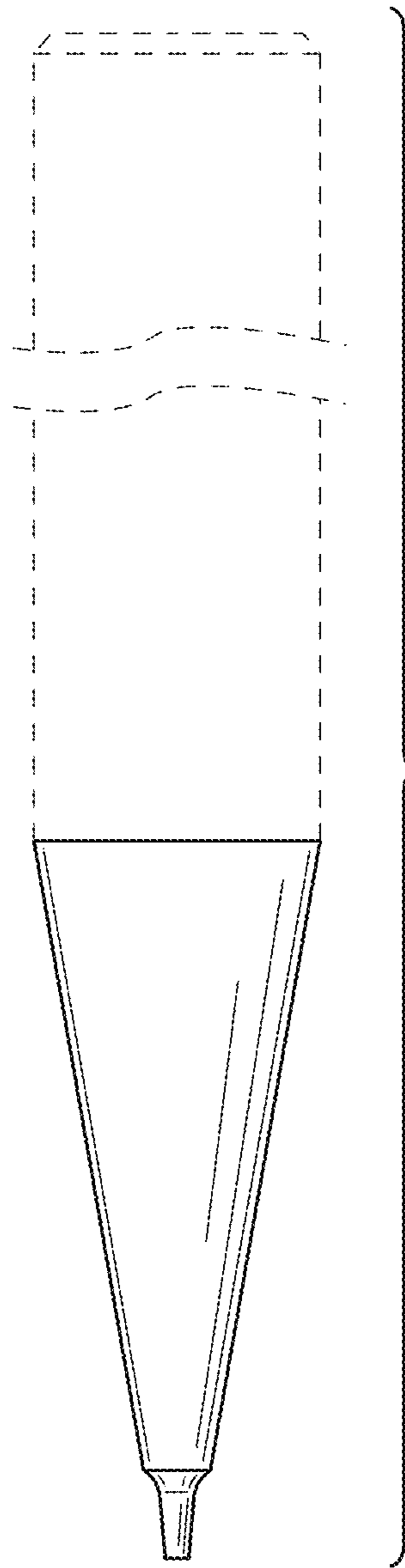


FIG. 2

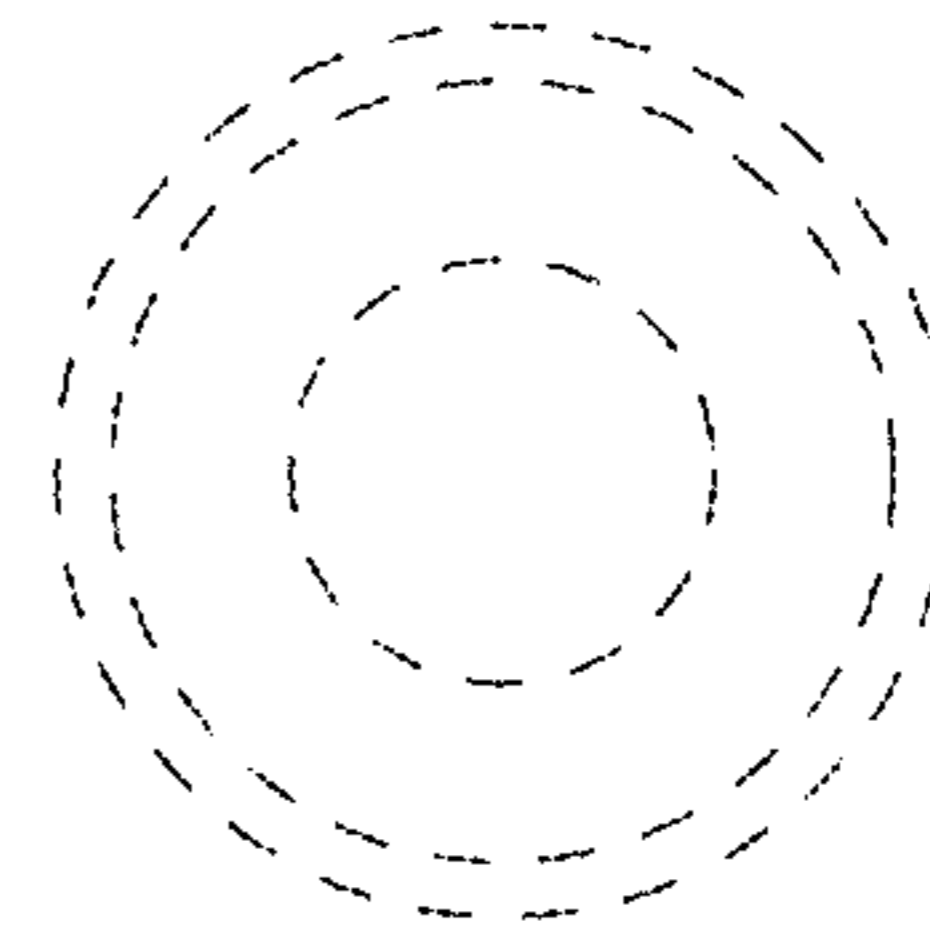


FIG. 3

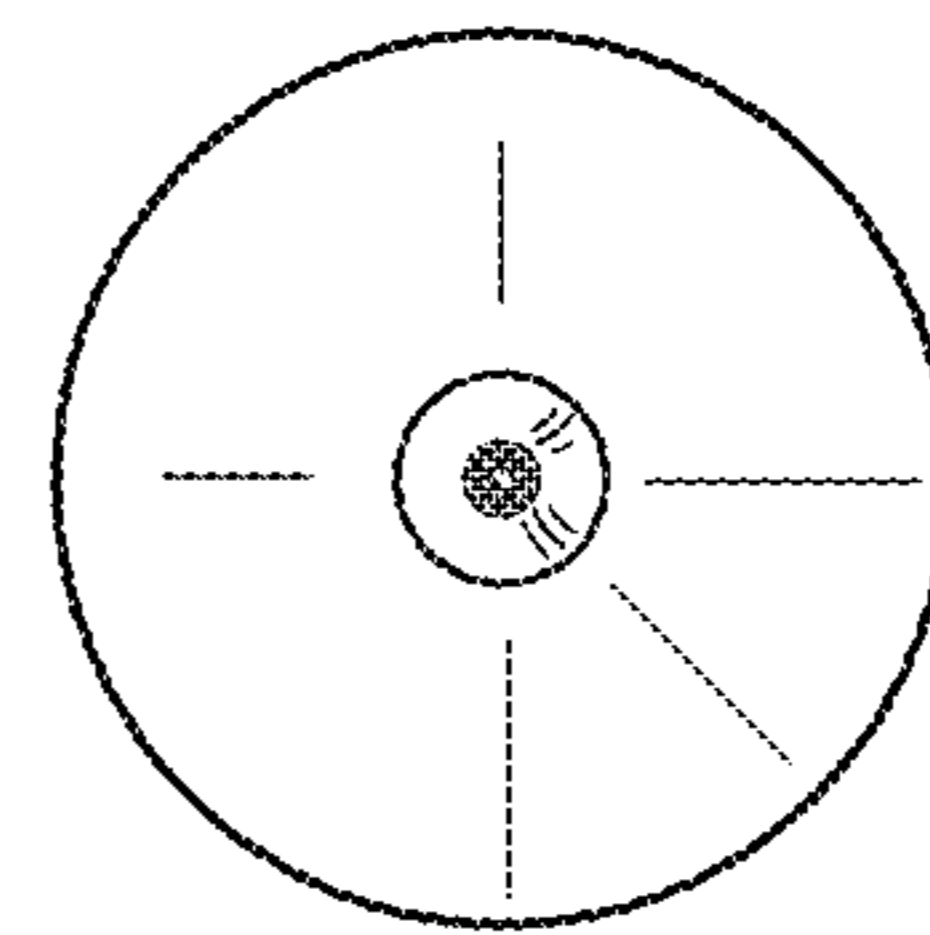


FIG. 4

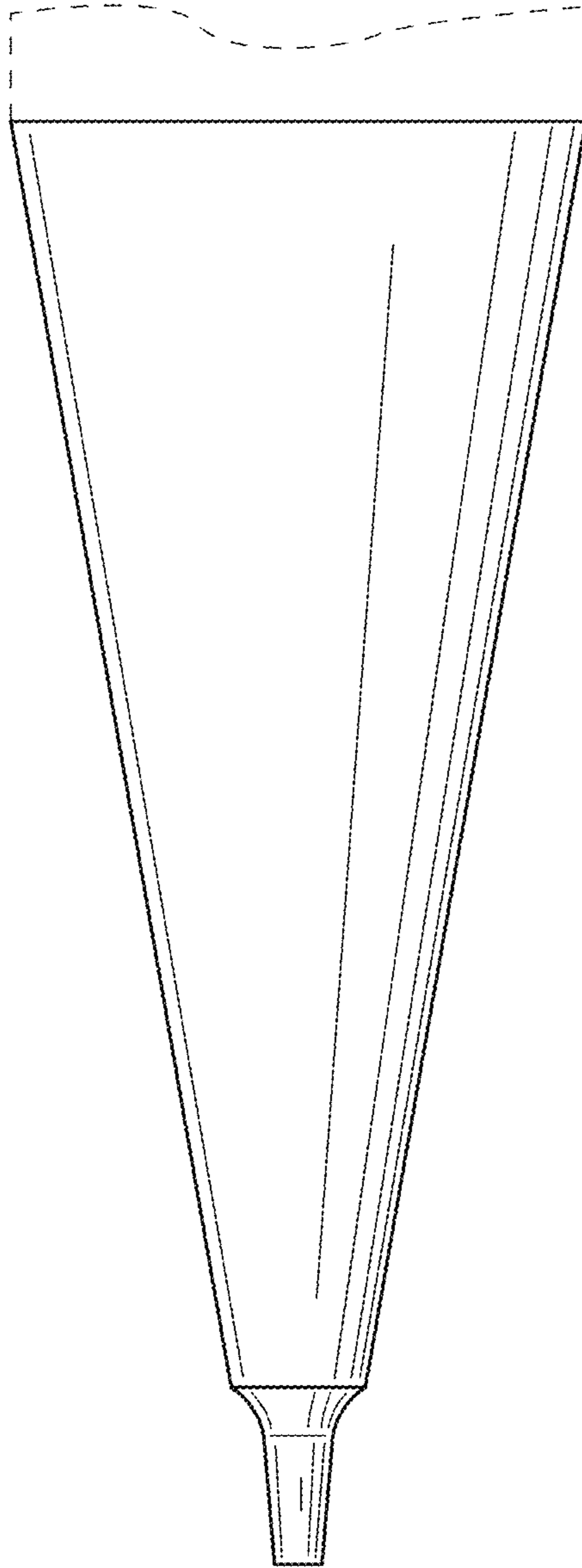


FIG.5

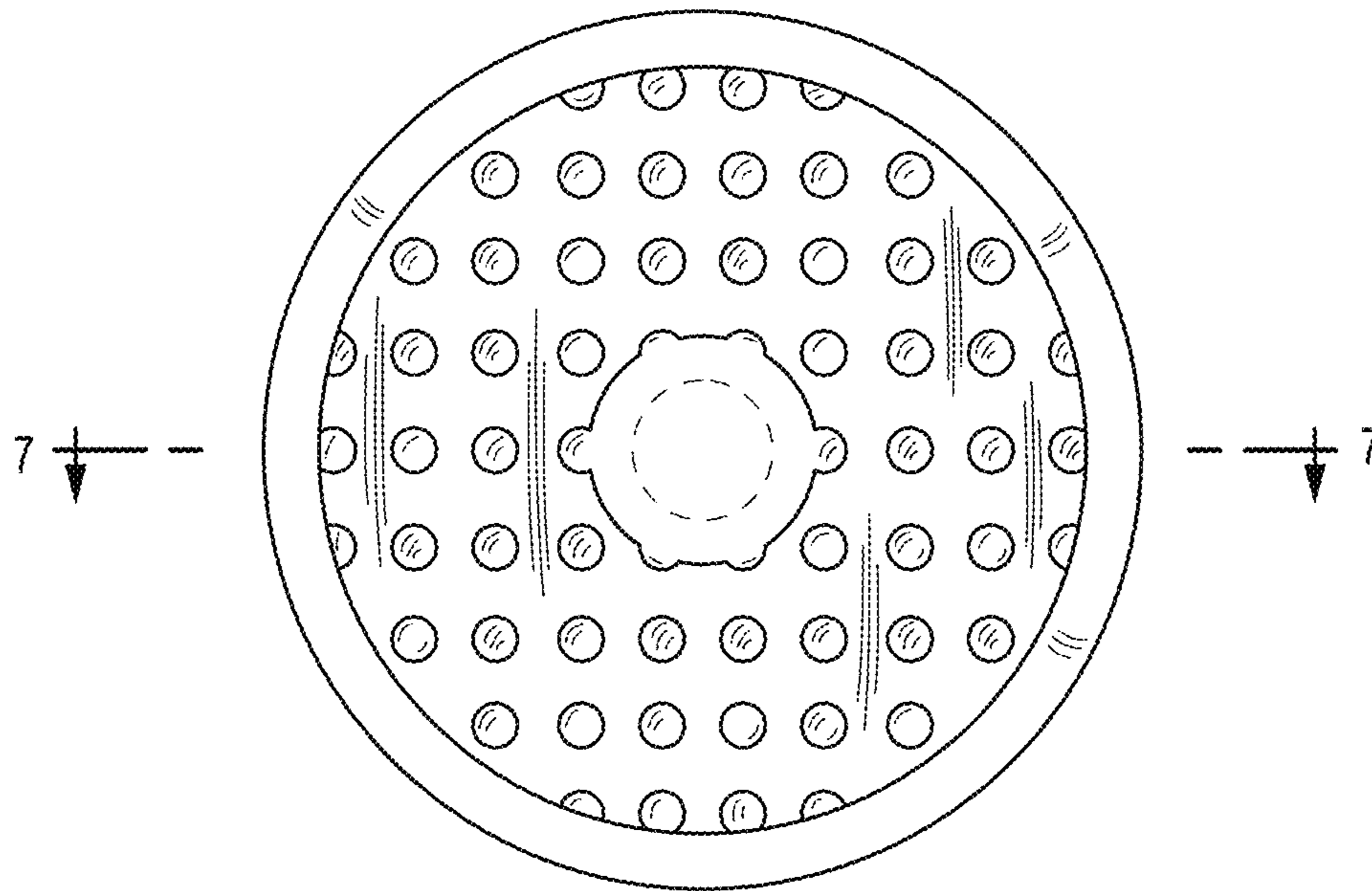


FIG. 6

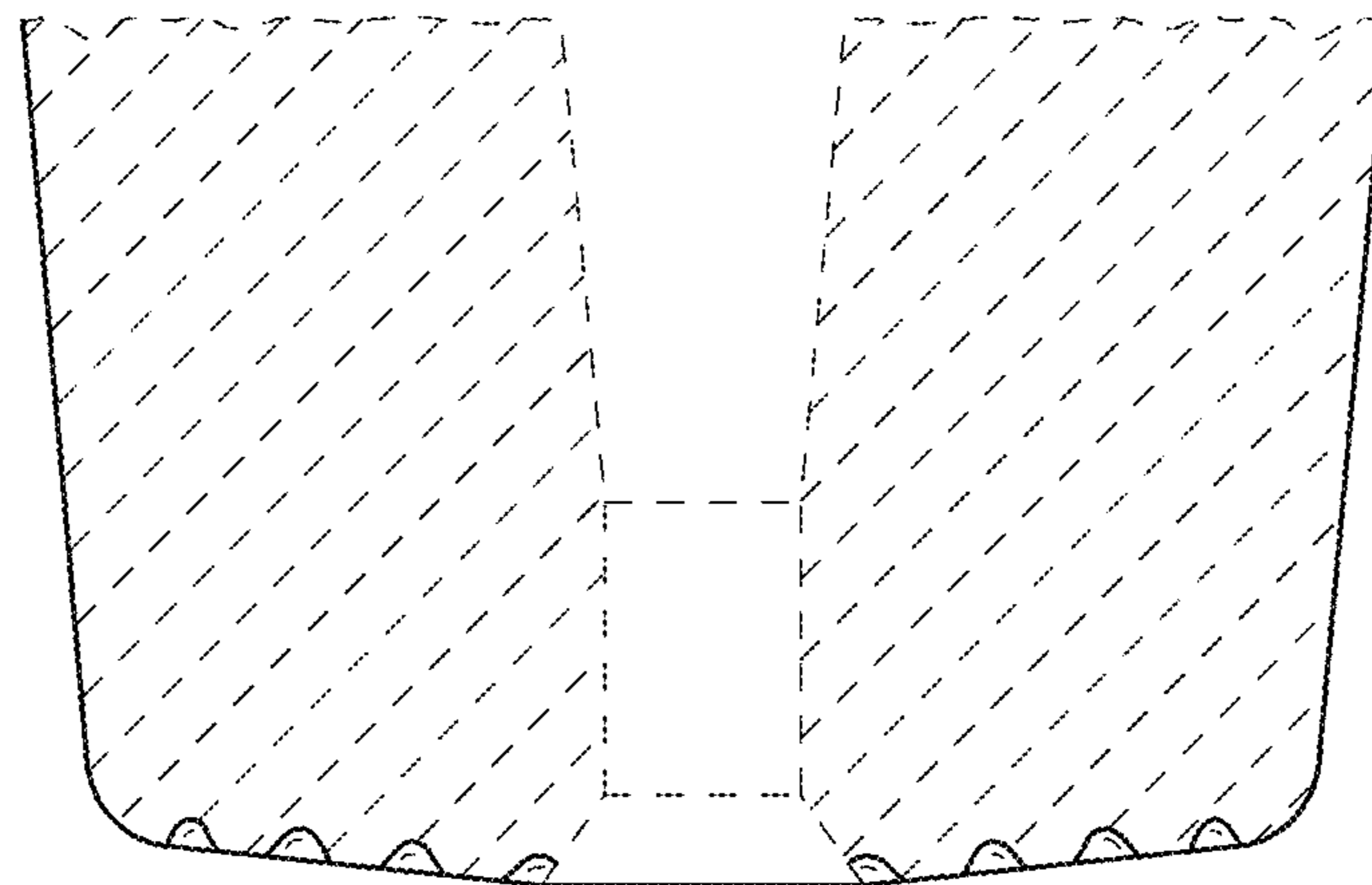


FIG. 7